



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



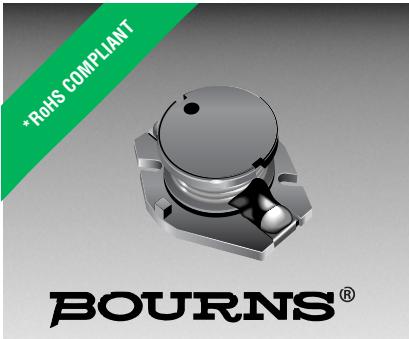
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Features

- Formerly J. W. Miller® model
- Available in E6 series
- Low profile of only 6.6 mm
- Inductance as low as 1 μ H
- RoHS compliant*

Applications

- Input/output of DC/DC converters
- Power supplies for:
 - Portable communication equipment
 - Camcorders
 - LCD TVs
 - Car radios

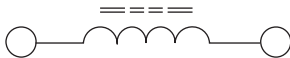
PM5022 Series - SMD Power Inductor

Electrical Specifications

Bourns Part No.	Inductance 100 kHz		Test Q Ref.	SRF Frequency (MHz)	Typ. (MHz)	RDC (m Ω)	I rms Max. (A)	I sat Typ. (A)
	(μ H)	Tol. %						
PM5022-1R0M-RC	1.0	± 20	21	7.96	100.0	4.0	10.0	30.00
PM5022-2R2M-RC	2.2	± 20	22	7.96	55.0	6.8	9.00	22.00
PM5022-3R3M-RC	3.3	± 20	22	7.96	40.0	9.8	7.60	17.00
PM5022-5R6M-RC	5.6	± 20	23	7.96	30.0	15.0	6.40	12.80
PM5022-8R2M-RC	8.2	± 20	22	7.96	27.0	20.0	7.00	9.40
PM5022-100M-RC	10	± 20	22	2.52	25.0	25.0	5.30	10.00
PM5022-150M-RC	15	± 20	20	2.52	17.0	35.0	4.30	8.00
PM5022-220M-RC	22	± 20	22	2.52	13.0	45.0	3.60	6.70
PM5022-330M-RC	33	± 20	24	2.52	11.0	68.0	3.00	5.40
PM5022-470M-RC	47	± 20	22	2.52	9.0	95.0	2.50	4.60
PM5022-680M-RC	68	± 20	22	2.52	8.0	130.0	2.10	3.80
PM5022-101<1>-RC	100	± 10	25	0.796	7.0	190.0	1.70	3.20
PM5022-151<1>-RC	150	± 10	23	0.796	5.0	270.0	1.40	2.60
PM5022-221<1>-RC	220	± 10	20	0.796	4.5	420.0	1.10	2.20
PM5022-331<1>-RC	330	± 10	18	0.796	3.5	580.0	1.00	1.80
PM5022-471<1>-RC	470	± 10	15	0.796	3.0	820.0	0.80	1.50
PM5022-681<1>-RC	680	± 10	12	0.796	2.5	1200.0	0.70	1.20
PM5022-102<1>-RC	1000	± 10	10	0.252	2.0	1800.0	0.50	1.00

<1> Enter tolerance code: K = ± 10 %, M = ± 20 %.

Electrical Schematic



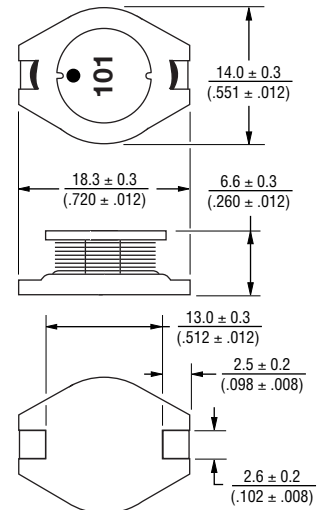
General Specifications

Test Voltage 0.1 V
 Reflow soldering 250 °C; 10 sec max.
 (In compliance with JEDEC,
 J-STD-020C, Table 4-2)
 Operating Temperature
 -40 °C to +125 °C
 (Temperature rise included)
 Storage Temperature
 -40 °C to +125 °C
 Resistance to Soldering Heat
 250 °C, 10 sec. max.

Materials

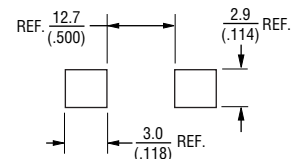
Core Ferrite DR
 Wire Enameled copper
 Base LCP E4008
 Terminal Cu/Sn
 Rated Current
 Ind. drop 10 % typ. at Isat
 Temperature Rise 40 °C max.
 at rated I rms
 Packaging 250 pcs. per reel

Product Dimensions



• = START OF WINDING

Recommended Layout



DIMENSIONS: $\frac{\text{MM}}{\text{(INCHES)}}$

*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.
 Specifications are subject to change without notice.

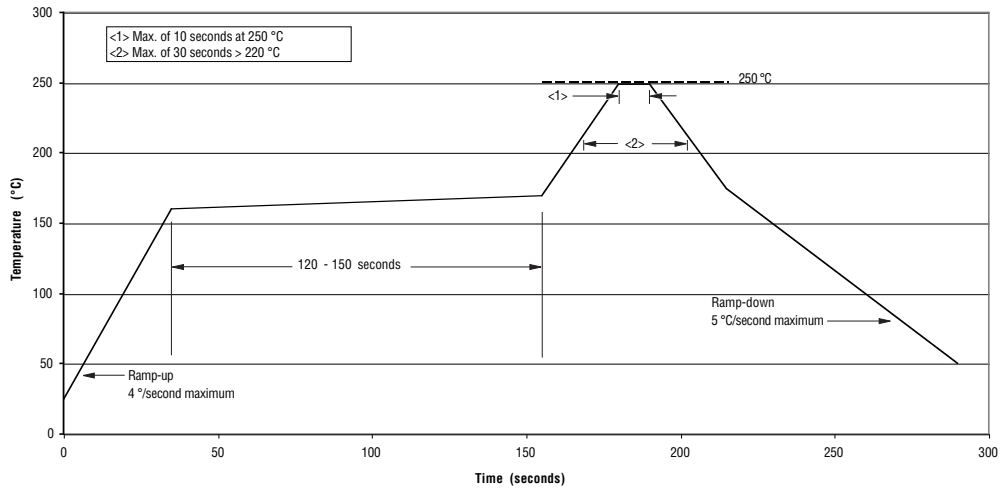
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.

Users should verify actual device performance in their specific applications.

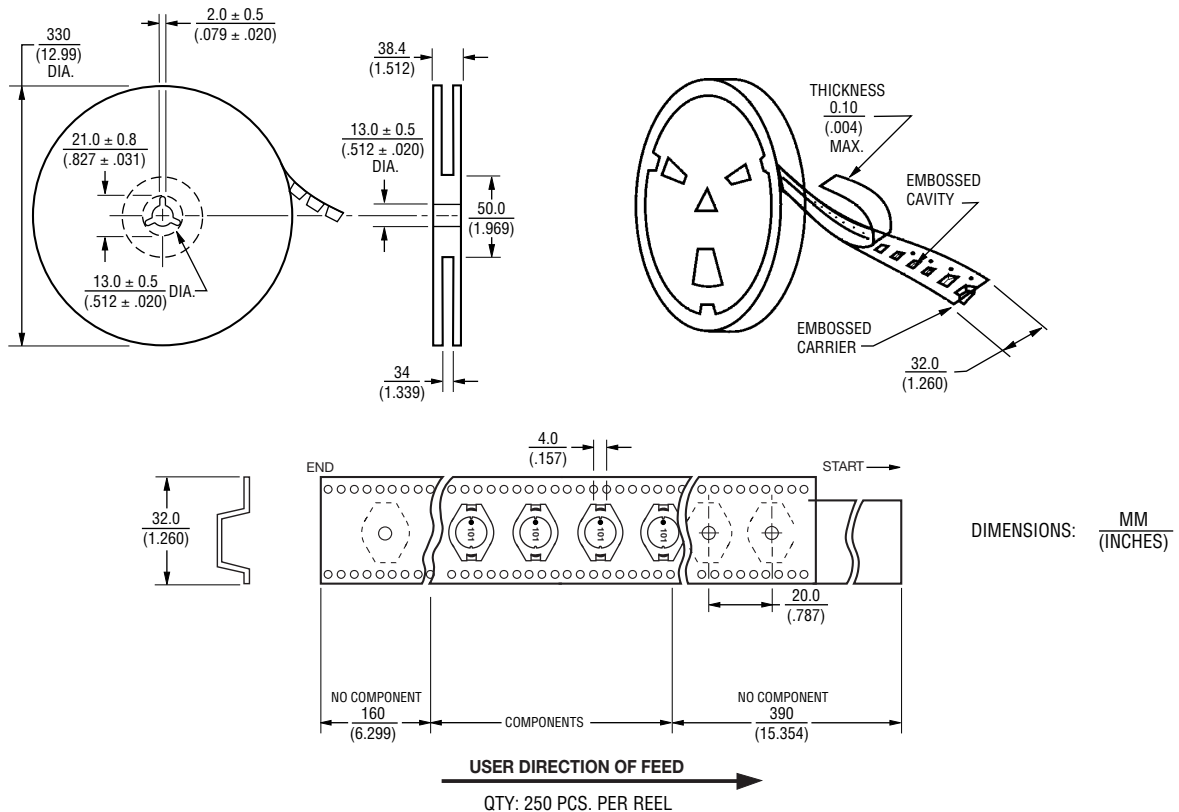
PM5022 Series - SMD Power Inductor

BOURNS®

Soldering Profile



Packaging Specifications



REV. 06/15

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